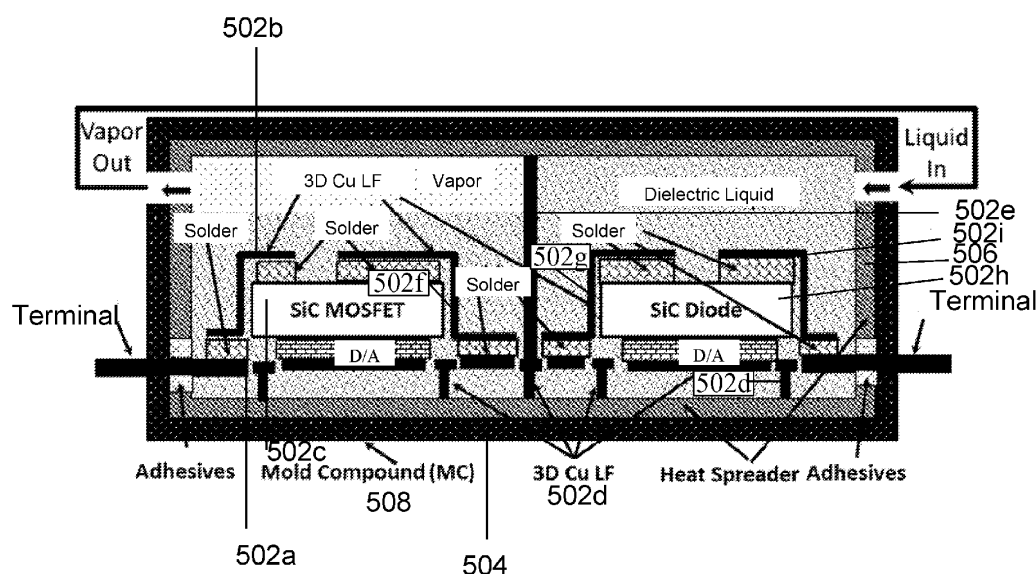




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(54) Title: POWER MODULE PACKAGE AND METHOD OF FORMING THE SAME

FIG. 5



(57) **Abstract:** Various embodiments may relate to a power module package. The power module package may include a power module including a first lead frame, a second lead frame, and at least one chip at least partially between the first lead frame and the second lead frame. The power module package may also include a first heat spreader attached to the first lead frame. The power module package may further include a second heat spreader also attached to the first lead frame such that the first lead frame, the first heat spreader and the second heat spreader form an enclosure defining a cavity containing the at least one chip. The enclosure may include an inlet configured to allow a cooling medium to flow into the cavity and an outlet configured to allow the cooling medium to flow out of the cavity.

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